# E·XFL

## Intel - 10AX057K2F40I1SG Datasheet



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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

#### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Discontinued at Digi-Key
Number of LABs/CLBs	217080
Number of Logic Elements/Cells	570000
Total RAM Bits	42082304
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.98V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10ax057k2f40i1sg

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# Intel<sup>®</sup> Arria<sup>®</sup> 10 Device Overview

The Intel<sup>®</sup> Arria<sup>®</sup> 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Market	Applications
Wireless	<ul><li>Channel and switch cards in remote radio heads</li><li>Mobile backhaul</li></ul>
Wireline	<ul> <li>40G/100G muxponders and transponders</li> <li>100G line cards</li> <li>Bridging</li> <li>Aggregation</li> </ul>
Broadcast	<ul> <li>Studio switches</li> <li>Servers and transport</li> <li>Videoconferencing</li> <li>Professional audio and video</li> </ul>
Computing and Storage	<ul><li>Flash cache</li><li>Cloud computing servers</li><li>Server acceleration</li></ul>
Medical	<ul><li>Diagnostic scanners</li><li>Diagnostic imaging</li></ul>
Military	<ul> <li>Missile guidance and control</li> <li>Radar</li> <li>Electronic warfare</li> <li>Secure communications</li> </ul>

#### Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

#### **Related Information**

Intel Arria 10 Device Handbook: Known Issues Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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# **Key Advantages of Intel Arria 10 Devices**

# Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	<ul> <li>Built on TSMC's 20 nm process technology</li> <li>60% higher performance than the previous generation of mid-range FPGAs</li> <li>15% higher performance than the fastest previous-generation FPGA</li> </ul>
High-bandwidth integrated transceivers	<ul> <li>Short-reach rates up to 25.8 Gigabits per second (Gbps)</li> <li>Backplane capability up to 12.5 Gbps</li> <li>Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)</li> </ul>
Improved logic integration and hard IP blocks	<ul> <li>8-input adaptive logic module (ALM)</li> <li>Up to 65.6 megabits (Mb) of embedded memory</li> <li>Variable-precision digital signal processing (DSP) blocks</li> <li>Fractional synthesis phase-locked loops (PLLs)</li> <li>Hard PCI Express Gen3 IP blocks</li> <li>Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)</li> </ul>
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	<ul> <li>Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC)</li> <li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li> </ul>
Advanced power savings	<ul> <li>Comprehensive set of advanced power saving features</li> <li>Power-optimized MultiTrack routing and core architecture</li> <li>Up to 40% lower power compared to previous generation of mid-range FPGAs</li> <li>Up to 60% lower power compared to previous generation of high-end FPGAs</li> </ul>

# **Summary of Intel Arria 10 Features**

#### Table 3. Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	<ul> <li>TSMC's 20-nm SoC process technology</li> <li>Allows operation at a lower V<sub>CC</sub> level of 0.82 V instead of the 0.9 V standard V<sub>CC</sub> core voltage</li> </ul>
Packaging	<ul> <li>1.0 mm ball-pitch Fineline BGA packaging</li> <li>0.8 mm ball-pitch Ultra Fineline BGA packaging</li> <li>Multiple devices with identical package footprints for seamless migration between different FPGA densities</li> <li>Devices with compatible package footprints allow migration to next generation high-end Stratix<sup>®</sup> 10 devices</li> <li>RoHS, leaded<sup>(1)</sup>, and lead-free (Pb-free) options</li> </ul>
High-performance FPGA fabric	<ul> <li>Enhanced 8-input ALM with four registers</li> <li>Improved multi-track routing architecture to reduce congestion and improve compilation time</li> <li>Hierarchical core clocking architecture</li> <li>Fine-grained partial reconfiguration</li> </ul>
Internal memory blocks	<ul> <li>M20K—20-Kb memory blocks with hard error correction code (ECC)</li> <li>Memory logic array block (MLAB)—640-bit memory</li> </ul>
	continued

<sup>&</sup>lt;sup>(1)</sup> Contact Intel for availability.



Feature		Description				
Embedded Hard IP blocks	Variable-precision DSP	<ul> <li>Native support for signal processing precision levels from 18 x 19 to 54 x 54</li> <li>Native support for 27 x 27 multiplier mode</li> <li>64-bit accumulator and cascade for systolic finite impulse responses (FIRs)</li> <li>Internal coefficient memory banks</li> <li>Preadder/subtractor for improved efficiency</li> <li>Additional pipeline register to increase performance and reduce power</li> <li>Supports floating point arithmetic:         <ul> <li>Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication.</li> <li>Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability.</li> <li>Dynamic accumulator reset control.</li> <li>Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.</li> </ul> </li> </ul>				
	Memory controller	DDR4, DDR3, and DDR3L				
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port				
	Transceiver I/O	<ul> <li>10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC)</li> <li>PCS hard IPs that support: <ul> <li>10-Gbps Ethernet (10GbE)</li> <li>PCIe PIPE interface</li> <li>Interlaken</li> <li>Gbps Ethernet (GbE)</li> <li>Common Public Radio Interface (CPRI) with deterministic latency support</li> <li>Gigabit-capable passive optical network (GPON) with fast lock-time support</li> </ul> </li> <li>13.5G JESD204b</li> <li>8B/10B, 64B/66B, 64B/67B encoders and decoders</li> <li>Custom mode support for proprietary protocols</li> </ul>				
Core clock networks	<ul> <li>667 MHz externa</li> <li>800 MHz LVDS in</li> <li>Global, regional, and</li> </ul>	c clocking, depending on the application: I memory interface clocking with 2,400 Mbps DDR4 interface terface clocking with 1,600 Mbps LVDS interface I peripheral clock networks are not used can be gated to reduce dynamic power				
Phase-locked loops (PLLs)	<ul> <li>Support integer r</li> <li>Fractional mode s</li> <li>Integer PLLs:         <ul> <li>Adjacent to gene</li> </ul> </li> </ul>	nthesis, clock delay compensation, and zero delay buffering (ZDB) node and fractional mode support with third-order delta-sigma modulation				
FPGA General-purpose I/Os (GPIOs)	On-chip termination	ry pair can be configured as receiver or transmitter (OCT) ended LVTTL/LVCMOS interfacing				
External Memory Interface	<ul> <li>Hard memory controller— DDR4, DDR3, and DDR3L support         <ul> <li>DDR4—speeds up to 1,200 MHz/2,400 Mbps</li> <li>DDR3—speeds up to 1,067 MHz/2,133 Mbps</li> </ul> </li> <li>Soft memory controller—provides support for RLDRAM 3<sup>(2)</sup>, QDR IV<sup>(2)</sup>, and QDR II+         <i>continued</i></li> </ul>					



Feature	Description					
Low-power serial transceivers	<ul> <li>Continuous operating range: <ul> <li>Intel Arria 10 GX—1 Gbps to 17.4 Gbps</li> <li>Intel Arria 10 GT—1 Gbps to 25.8 Gbps</li> </ul> </li> <li>Backplane support: <ul> <li>Intel Arria 10 GX—up to 12.5</li> <li>Intel Arria 10 GT—up to 12.5</li> </ul> </li> <li>Extended range down to 125 Mbps with oversampling</li> <li>ATX transmit PLLs with user-configurable fractional synthesis capability</li> <li>Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module</li> <li>Adaptive linear and decision feedback equalization</li> <li>Transmitter pre-emphasis and de-emphasis</li> <li>Dynamic partial reconfiguration of individual transceiver channels</li> </ul>					
HPS (Intel Arria 10 SX devices only)	Processor and system       • Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability         • 256 KB on-chip RAM and 64 KB on-chip ROM         • System peripherals—general-purpose timers, watchdog timers, di memory access (DMA) controller, FPGA configuration manager, ar clock and reset managers         • Security features—anti-tamper, secure boot, Advanced Encryptior Standard (AES) and authentication (SHA)         • ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage	nd n				
	<ul> <li>External interfaces</li> <li>Hard memory interface—Hard memory controller (2,400 Mbps DE and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) fl controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller</li> <li>Communication interface—10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I<sup>2</sup>C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)</li> </ul>	lash				
	Interconnects to core       • High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write         • HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to iss transactions to slaves in the HPS, and vice versa         • Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port         • FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller					
Configuration	<ul> <li>Tamper protection—comprehensive design protection to protect your valuable IP investment</li> <li>Enhanced 256-bit advanced encryption standard (AES) design security with authentication</li> <li>Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3</li> </ul>					
	continue	d				

 $<sup>^{(2)}\,</sup>$  Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



ES : Engineering sample

RoHS

**FPGA Fabric** 

Speed Grade

1 (fastest)

2 3

G : RoHS6 N : RoHS5 Contact Intel P : Leaded for availability

# **Available Options**

Family Variant .....

090 : 900K logic elements 115 : 1,150K logic elements

25.8 Gbps transceivers

Transceiver

1 (fastest)

2

Speed Grade

T : GT variant

Logic Density



Package Code

45 : 1,932 pins, 45 mm x 45 mm

## Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices



# **Maximum Resources**

#### Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	urce	Produ	ct Line
		GT 900	GT 1150
Logic Elements (LE) (K)		900	1,150
ALM		339,620	427,200
Register	Register		1,708,800
Memory (Kb)	M20K	48,460	54,260
	MLAB	9,386	12,984
Variable-precision DSP Block		1,518	1,518
18 x 19 Multiplier		3,036	3,036
PLL	Fractional Synthesis	32	32
	I/O	16	16
Transceiver	17.4 Gbps	72 (5)	72 <sup>(5)</sup>
	25.8 Gbps	6	6
GPIO <sup>(6)</sup>		624	624
LVDS Pair <sup>(7)</sup>		312	312
PCIe Hard IP Block		4	4
Hard Memory Controller		16	16

#### **Related Information**

#### Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

# Package Plan

#### Table 11.Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR		
GT 900	—	624	72		
GT 1150	_	624	72		

<sup>&</sup>lt;sup>(5)</sup> If all 6 GT channels are in use, 12 of the GX channels are not usable.

<sup>&</sup>lt;sup>(6)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>&</sup>lt;sup>(7)</sup> Each LVDS I/O pair can be used as differential input or output.



## **Maximum Resources**

#### Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multip	18 x 19 Multiplier		384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO <sup>(8)</sup>		288	288	384	384	492	696	696
LVDS Pair <sup>(9)</sup>		120	120	168	168	174	324	324
PCIe Hard IP Block		1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-As Processor	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes

# Package Plan

# Table 13.Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

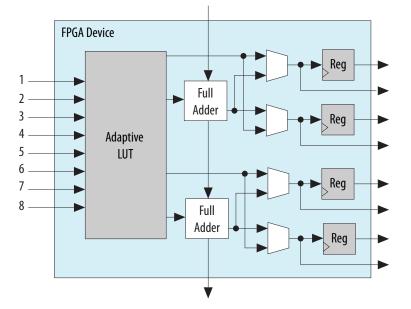
Product Line	ne U19 (19 mm × 19 mm, 484-pin UBGA)			F27 (27 mm × 27 mm, 672-pin FBGA)		F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	_	-	-
SX 220	48	144	6	48	192	12	48	240	12	_	-	-
SX 270	-	-	_	48	192	12	48	312	12	48	336	24
SX 320	-	-	_	48	192	12	48	312	12	48	336	24
continued												

<sup>&</sup>lt;sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9)</sup> Each LVDS I/O pair can be used as differential input or output.



#### Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

# **Variable-Precision DSP Block**

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

#### Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

#### Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block		put and Output ons Operator	18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder		
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode	Summed with 36 bit Input		
AIntel Arria 10 GX	GX 160	156	312	156	156	156		
GX	GX 220	192	384	192	192	192		
	GX 270	830	1,660	830	830	830		
	GX 320	984	1,968	984	984	984		
	GX 480	1,368	2,736	1,368	1,368	1,368		
	GX 570	1,523	3,046	1,523	1,523	1,523		
	GX 660	1,687	3,374	1,687	1,687	1,687		
	GX 900	1,518	3,036	1,518	1,518	1,518		
	GX 1150	1,518	3,036	1,518	1,518	1,518		
Intel Arria 10	GT 900	1,518	3,036	1,518	1,518	1,518		
GT	GT 1150	1,518	3,036	1,518	1,518	1,518		
Intel Arria 10	SX 160	156	312	156	156	156		
SX	SX 220	192	384	192	192	192		
	SX 270	830	1,660	830	830	830		
continue								



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
  - Conventional integer mode equivalent to the general purpose PLL
  - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

# I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

# **FPGA General Purpose I/O**

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
  - $-\,$  Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
  - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V<sub>OD</sub>) and programmable pre-emphasis



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

#### **Related Information**

PCS Features on page 30

# **Low Power Serial Transceivers**

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



## Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



# **PMA Features**

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 <sup>(12)</sup> to 2.97	Native PHY	Standard PCS

## **Related Information**

#### Intel Arria 10 Transceiver PHY User Guide

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

# SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

<sup>&</sup>lt;sup>(12)</sup> The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



# Table 24.Improvements in 20 nm HPS

This table lists the key improvements of the 20 nm HPS compared to the 28 nm HPS.

Advantages/ Improvements	Description		
Increased performance and overdrive capability	While the nominal processor frequency is 1.2 GHz, the 20 nm HPS offers an "overdrive" feature which enables a higher processor operating frequency. This requires a higher su voltage value that is unique to the HPS and may require a separate regulator.		
Increased processor memory bandwidth and DDR4 support	Up to 64-bit DDR4 memory at 2,400 Mbps support is available for the processor. The hard memory controller for the HPS comprises a multi-port front end that manages connections to a single port memory controller. The multi-port front end allows logic core and the HPS to share ports and thereby the available bandwidth of the memory controller.		
Flexible I/O sharing	<ul> <li>An advanced I/O pin muxing scheme allows improved sharing of I/O between the HPS and the core logic. The following types of I/O are available for SoC:</li> <li>17 dedicated I/Os—physically located inside the HPS block and are not accessible to logic within the core. The 17 dedicated I/Os are used for HPS clock, resets, and interfacing with boot devices, QSPI, and SD/MMC.</li> </ul>		
	• 48 direct shared I/O—located closest to the HPS block and are ideal for high speed HPS peripherals such as EMAC, USB, and others. There is one bank of 48 I/Os that supports direct sharing where the 48 I/Os can be shared 12 I/Os at a time.		
	• Standard (shared) I/O—all standard I/Os can be shared by the HPS peripherals and any logic within the core. For designs where more than 48 I/Os are required to fully use all the peripherals in the HPS, these I/Os can be connected through the core logic.		
EMAC core	Three EMAC cores are available in the HPS. The EMAC cores enable an application to support two redundant Ethernet connections; for example, backplane, or two EMAC cores for managing IEEE 1588 time stamp information while allowing a third EMAC core for debug and configuration. All three EMACs can potentially share the same time stamps, simplifying the 1588 time stamping implementation. A new serial time stamp interface allows core logic to access and read the time stamp values. The integrated EMAC controllers can be connected to external Ethernet PHY through the provided MDIO or $I^2C$ interface.		
On-chip memory	The on-chip memory is updated to 256 KB support and can support larger data sets and real time algorithms.		
ECC enhancements	Improvements in L2 Cache ECC management allow identification of errors down to the address level. ECC enhancements also enable improved error injection and status reporting via the introduction of new memory mapped access to syndrome and data signals.		
HPS to FPGA Interconnect Backbone	Although the HPS and the Logic Core can operate independently, they are tightly coupled via a high-bandwidth system interconnect built from high-performance ARM AMBA AXI bus bridges. IP bus masters in the FPGA fabric have access to HPS bus slaves via the FPGA-to-HPS interconnect. Similarly, HPS bus masters have access to bus slaves in the core fabric via the HPS-to-FPGA bridge. Both bridges are AMBA AXI-3 compliant and support simultaneous read and write transactions. Up to three masters within the core fabric can share the HPS SDRAM controller with the processor. Additionally, the processor can be used to configure the core fabric under program control via a dedicated 32-bit configuration port		
FPGA configuration and HPS booting	The FPGA fabric and HPS in the SoCs are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power. You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility.		
Security	New security features have been introduced for anti-tamper management, secure boot, encryption (AES), and authentication (SHA).		



## **System Peripherals and Debug Access Port**

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

#### **HPS-FPGA AXI Bridges**

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI<sup>m</sup>) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS–FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

#### **HPS SDRAM Controller Subsystem**

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon<sup>®</sup> Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



# **FPGA Configuration and HPS Booting**

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

## **Hardware and Software Development**

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux\*, VxWorks\*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

# **Dynamic and Partial Reconfiguration**

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

# **Dynamic Reconfiguration**

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

# **Partial Reconfiguration**

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
  - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
  - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

# **Enhanced Configuration and Configuration via Protocol**

## Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security <sup>(1</sup> 4)	Partial Reconfiguration (15)	Remote System Update
JTAG	1 bit	33	33	_	-	Yes <sup>(16)</sup>	-
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes <sup>(16)</sup>	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes <sup>(16)</sup>	Parallel Flash Loader (PFL) IP core
					•	со	ntinued

<sup>&</sup>lt;sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>&</sup>lt;sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>&</sup>lt;sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>&</sup>lt;sup>(16)</sup> Partial configuration can be performed only when it is configured as internal host.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V<sub>CC</sub> while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- Low Static Power Options—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

# **Incremental Compilation**

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

# **Document Revision History for Intel Arria 10 Device Overview**

Document Version	Changes
2018.04.09	Updated the lowest $V_{CC}$ from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	• Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.
		<ul> <li>Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in <i>Memory Standards Supported by the Soft</i> <i>Memory Controller</i> table.</li> </ul>
		Updated transceiver backplane capability to 12.5 Gbps.
		• Removed transceiver speed grade 5 in <i>Sample Ordering Core and Available Options for Intel Arria 10 GX Devices</i> figure.
	1	continued

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September 2017 July 2017 July 2017 May 2017 May 2017 March 2017	2017.09.20 2017.07.13 2017.07.06 2017.05.08	<ul> <li>Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from <i>Sample Ordering Core and Available Options for Intel Arria 10 GT Devices</i> figure.</li> <li>Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps.</li> <li>Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from <i>PMA Features of the Transceivers in Intel Arria 10 Devices</i> table.</li> <li>Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps.</li> <li>Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".</li> <li>Added automotive temperature option to Intel Arria 10 GX device family.</li> <li>Corrected protocol names with "1588" to "IEEE 1588v2".</li> <li>Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants.</li> </ul>
July 2017 July 2017 May 2017	2017.07.13 2017.07.06 2017.05.08	<ul> <li>1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps.</li> <li>Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".</li> <li>Added automotive temperature option to Intel Arria 10 GX device family.</li> <li>Corrected protocol names with "1588" to "IEEE 1588v2".</li> <li>Updated the vertical migration table to remove vertical migration</li> </ul>
July 2017 May 2017	2017.07.06 2017.05.08	<ul> <li>available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".</li> <li>Added automotive temperature option to Intel Arria 10 GX device family.</li> <li>Corrected protocol names with "1588" to "IEEE 1588v2".</li> <li>Updated the vertical migration table to remove vertical migration</li> </ul>
May 2017	2017.05.08	<ul> <li>Corrected protocol names with "1588" to "IEEE 1588v2".</li> <li>Updated the vertical migration table to remove vertical migration</li> </ul>
		Updated the vertical migration table to remove vertical migration
March 2017		Removed all "Preliminary" marks.
	2017.03.15	<ul> <li>Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices.</li> <li>Rebranded as Intel.</li> </ul>
October 2016	2016.10.31	<ul> <li>Removed package F36 from Intel Arria 10 GX devices.</li> <li>Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.</li> </ul>
May 2016	2016.05.02	<ul> <li>Updated the FPGA Configuration and HPS Booting topic.</li> <li>Remove V<sub>CC</sub> PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices.</li> <li>Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA.</li> <li>Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.</li> </ul>
February 2016	2016.02.11	<ul> <li>Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally.</li> <li>Revised the state for Core clock networks in the Summary of Features topic.</li> <li>Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table.</li> <li>Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table.</li> <li>Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table.</li> <li>Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure.</li> <li>Changed the transceiver parameters in the "Low Power Serial Transceivers" section.</li> <li>Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table.</li> <li>Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure.</li> <li>Changed the datarates for GT devices in the "PMA Features" section.</li> <li>Changed the datarates for GT devices in the "PCS Features" section.</li> </ul>

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Date	Version	Changes
December 2015	2015.12.14	• Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.
		Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.
November 2015	2015.11.02	• Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.
		Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in <b>Number of Multipliers in Intel Arria 10</b> <b>Devices</b> table.
		<ul><li>Updated the available options for Arria 10 GX, GT, and SX.</li><li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li></ul>
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	<ul> <li>Added support for 13.5G JESD204b in the Summary of Features table.</li> <li>Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.</li> </ul>
		Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.
		Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.
January 2015	2015.01.23	Added floating point arithmetic features in the Summary of Features table.
		• Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.
		Updated the table that lists the memory standards supported by Intel Arria 10 devices.
		<ul> <li>Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2.</li> <li>Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller.</li> </ul>
		Added soft memory controller support for QDR IV.
		• Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.
		• Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.
		Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.
		Added a feature for fractional synthesis PLLs: PLL cascading.
		Updated the HPS programmable general-purpose I/Os from 54 to 62.
September 2014	2014.09.30	• Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.
		• Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.
		<ul> <li>Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.</li> </ul>
		continued